



PATENT  
0152-0668P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: Matsuyoshi NAKAGAWA et al. Conf.:  
Appl. No.: 10/722,450 Group: UNASSIGNED  
Filed: November 28, 2003 Examiner: UNASSIGNED  
For: THERMOPLASTIC RESIN COMPOSITION AND  
MOLDINGS OF THE SAME

PRELIMINARY AMENDMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

February 26, 2004

Sir:

The following preliminary amendments and remarks are respectfully submitted in connection with the above-identified application.

This amendment includes: amendments to the specification, amendments to the Abstract and Remarks.